Preferred Device

Sensitive Gate Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed for high volume, low cost, industrial and consumer applications such as motor control, process control, temperature, light and speed control.

Features

- Small Size
- Passivated Die for Reliability and Uniformity
- Low Level Triggering and Holding Characteristics
- Surface Mount Lead Form Case 369C
- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V Machine Model, C > 400 V
- Pb-Free Packages are Available

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

 Epoxy Meets UL 94 V-0 @ 0.125 in ESD Ratings: Human Body Model, Machine Model, C > Pb-Free Packages are Available MAXIMUM RATINGS (T_J = 25°C unless of 	3B > 80 400 V		34	子 ^表 。CY
Rating	Symbol	Value	Unit	
Peak Repetitive Off–State Voltage (Note 1) (T _J = -40 to 110°C, Sine Wave, 50 to 60 Hz, Gate Open) MCR716 MCR718	V _{DRM,} V _{RRM}	400 600	V	
On–State RMS Current (180° Conduction Angles; T _C = 90°C)	I _{T(RMS)}	4.0	Α	N
Average On–State Current (180° Conduction Angles; T _C = 90°C)	I _{T(AV)}	2.6	Α	
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T _J = 110°C)	I _{TSM}	25	Α	
Circuit Fusing Consideration (t = 8.3 msec)	l ² t	2.6	A ² sec	
Forward Peak Gate Power (Pulse Width ≤ 1.0 μsec, T _C = 90°C)	P _{GM}	0.5	W	Y WW
Forward Average Gate Power (t = 8.3 msec, T _C = 90°C)	P _{G(AV)}	0.1	W	MCR G
Forward Peak Gate Current (Pulse Width ≤ 1.0 μsec, T _C = 90°C)	I _{GM}	0.2	Α	
Operating Junction Temperature Range	TJ	-40 to +110	°C	
Storage Temperature Range	T _{stg}	-40 to +150	°C	1

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

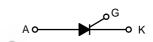
1. V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



ON Semiconductor®

http://onsemi.com

SCRs 4.0 AMPERES RMS 400 - 600 VOLTS





DPAK CASE 369C STYLE 4

MARKING DIAGRAM



= Year WW = Work Week MCR71x = Device Code x = M or NG = Pb-Free Package

PIN ASSIGNMENT			
1	Cathode		
2	Anode		
3	Gate		
4	Anode		

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	3.0	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	80	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	T_L	260	°C

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted.)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Peak Repetitive Forward or Reverse Blocking Current; R $(V_{AK} = Rated V_{DRM})$	$t_{GK} = 1 \text{ k}\Omega \text{ (Note 3)}$ $T_C = 25^{\circ}\text{C}$ $T_C = 110^{\circ}\text{C}$	I _{DRM} I _{RRM}	- -	_ _	10 200	μΑ
ON CHARACTERISTICS						
Peak Reverse Gate Blocking Voltage ($I_{GR} = 10 \mu A$)		V_{RGM}	10	12.5	18	V
Peak Reverse Gate Blocking Current (V _{GR} = 10 V)		I _{RGM}	-	-	1.2	μΑ
Peak Forward On-State Voltage (Note 4) (I _{TM} = 5.0 A Peak) (I _{TM} = 8.2 A Peak)		V _{TM}	_ _	1.3 1.5	1.5 2.2	V
Gate Trigger Current (Continuous dc) (Note 5) $(V_D = 12 \text{ Vdc}, R_L = 30 \text{ Ohms})$	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	let	1.0	25 -	75 300	μΑ
Gate Trigger Voltage (Continuous dc) (Note 5) (V _D = 12 Vdc, R _L = 30 Ohms)	$T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$ $T_{C} = 110^{\circ}C$	V _G T	0.3 - 0.2	0.55 - -	0.8 1.0 –	V
Holding Current (Note 3) (V _D = 12 Vdc, Initiating Current = 200 mA, Gate Open)	$T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$	lн	0.4	1.0	5.0 10	mA
Latching Current (Note 3) $ (V_D = 12 \text{ Vdc}, I_G = 2.0 \text{ mA}, T_C = 25^{\circ}\text{C}) $ $ (V_D = 12 \text{ Vdc}, I_G = 2.0 \text{ mA}, T_C = -40^{\circ}\text{C}) $		lι		_ _	5.0 10	mA
Total Turn-On Time (Source Voltage = 12 V, $R_S = 6 \text{ k}\Omega$, $I_T = 8 \text{ A(pk)}$, $R_{GK} = (V_D = \text{Rated V}_{DRM}$, Rise Time = 20 ns, Pulse Width =		t _{gt}	-	2.0	5.0	μS
DYNAMIC CHARACTERISTICS						
Critical Rate of Rise of Off–State Voltage $(V_D = 0.67 \text{ x Rated } V_{DRM}, R_{GK} = 1 \text{ k}\Omega,$ Exponential W	aveform, T _J = 110°C)	dv/dt	5.0	10	_	V/μs
Repetitive Critical Rate of Rise of On-State Current		di/dt	-	-	100	A/μs

^{2.} Case 369C, when surface mounted on minimum recommended pad size.

(f = 60 Hz, I_{PK} = 30 A, PW = 100 μ s, dIG/dt = 1 A/ μ s)

ORDERING INFORMATION

Device	Package	Shipping [†]
MCR716T4	DPAK	
MCR716T4G	DPAK (Pb-Free)	2500 / Tape and Reel
MCR718T4	DPAK	2500 / Tape and Reel
MCR718T4G	DPAK (Pb-Free)	

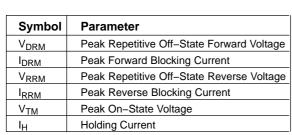
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

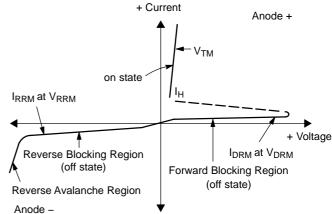
Ratings apply for negative gate voltage or R_{GK} = 1 kΩ. Devices shall not have a positive gate voltage concurrently with a negative voltage
on the anode. Devices should not be tested with a constant current source for forward and reverse blocking capability such that the voltage
applied exceeds the rated blocking voltage.

^{4.} Pulse Test: Pulse Width \leq 2 ms, Duty Cycle \leq 2%.

^{5.} R_{GK} current not included in measurements.

Voltage Current Characteristic of SCR





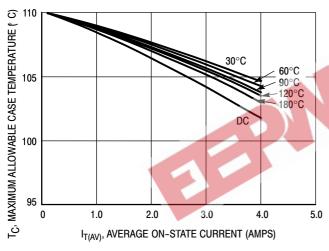
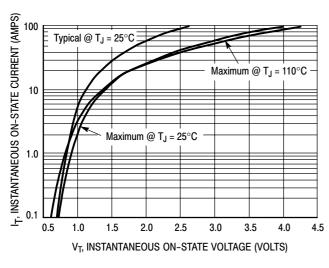
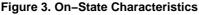


Figure 1. Average Current Derating

Figure 2. On-State Power Dissipation





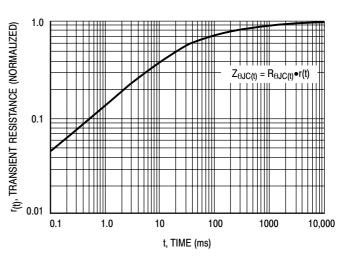


Figure 4. Transient Thermal Response

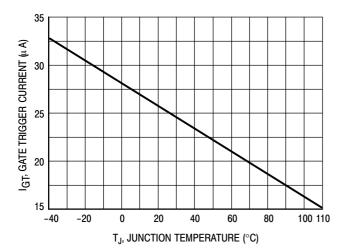


Figure 5. Typical Gate Trigger Current versus Junction Temperature

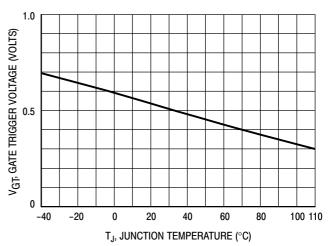


Figure 6. Typical Gate Trigger Voltage versus Junction Temperature



Figure 7. Typical Holding Current versus Junction Temperature

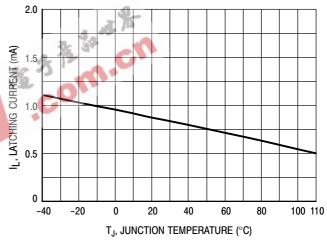
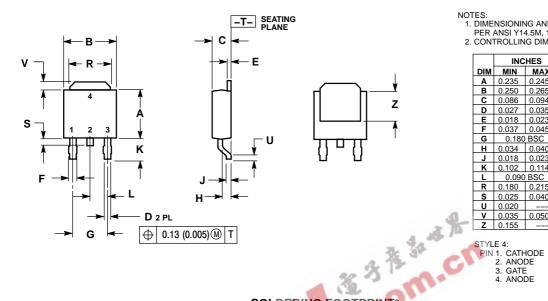


Figure 8. Typical Latching Current versus Junction Temperature

PACKAGE DIMENSIONS

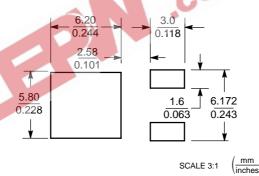
DPAK CASE 369C **ISSUE O**



- NOTES:
 1. DIMENSIONING AND TOLERANCING
- PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETER	
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.22
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180	BSC	4.58	BSC
Н	0.034	0.040	0.87	1.01
ſ	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090	0.090 BSC		BSC
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020		0.51	
٧	0.035	0.050	0.89	1.27
Z	0.155		3.93	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and up are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice ON Semiconductor and war registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights or the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized large steps SCILLC is an Equal to the desiring or manufacture of the party of t associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA **Phone**: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051 Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative